



Material declaration form

General information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		*: Required Field
Supplier information			
Company name*	STMicroelectronics	Response date*	2024-12-04
Authorized representative*	Antonella Lanzafame	Representative title	APMS Material Declaration Champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance *	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Manufacturing item number	Manufacturing item name	Version	Manufacturing site	Date
LSM6DSV320XTR	77AA*MY3ZABD	A	CA2A	2024-12-04
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	13.20	mg	Each	ECOPACK® 3
Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony			

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
1	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Not Applicable	Nickel/Gold (Ni/Au), electrolytic	Copper Alloy	0	
Package designator	Package Size	Number of instances	Shape	
LGA	3 x 2.5	14	Flat	
Comment	VFLGA 2.5MM X 3MM X 0.83 TYP 14L			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	
7c-I	7c-I-Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectric devices, or in a glass or ceramic matrix compound	

QueryList : ELV directive : 2000/53/EC amended 2020/363_ March 2020		Response
QUERY		Response
1 - Product(s) meets EU ELV requirement without any exemptions		false
2 - Product(s) meets EU ELV requirements by application of the selected exemption(s)		true
Exemption Id.	Description	
10(a)	10(a) - Electrical and electronic components which contain lead in a glass or ceramic, in a glass or ceramic matrix compound, in a glass-ceramic material, or in a glass-ceramic matrix compound.	

QueryList : California Prop65 list, dated 29th December 2023			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			false
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			true
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.105	Die	7955
Lead	0.197	glass	14939
Lead-Borate Glass	0.327	passivation	24773

QueryList : Chinese RoHS , references : SJT 11364 – 2014 and GBT 26572 – 2014					Response
1 - Product(s) requires marking for the presence of restricted substances and must be marked with an Environmental Protection Use Period under China's Measures for Administration of the control of pollution by Electronic Information Products					false
2 - Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products					false
Hazardous substance					
Lead (Pb)	Cadmium (Cd)	Mercury (Hg)	Hexavalent Chromium (Cr VI)	PBB & PBDE	
X	O	O	O	O	
Dies					
is Homogeneous Material containing Lead					



QueryList : REACH-7th November 2024				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	Amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Homogeneous Material above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	Amount in homogeneous material (mg)	Application - homogeneous material	ppm in homogeneous material
QueryList : Korea Chemical Control Act_ 27 Dec 2017 update				Response
The Product does contain at least one of the substances listed in Chemical Control Act				false



QueryList : Responsible metals sourcing				Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.				true

QueryList : China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020				Response
The product contains adhesives identified under GB 33372				false

QueryList:Stockholm Convention Persistent Organic Pollutants (POP)				Response
Product is compliant with Annex A, B and C of Stockholm Convention Persistent Organic Pollutants				true

QueryList: EU Ship Recycling Regulation No. 1257/2013				Response
Product contains hazardous materials listed in Annex II of EU Ship Recycling Regulation No.1257/2013 and 2009/16/EC Directive				True

PFAS/PTFE Declaration				Response
QUERY				Response
The product is containing at least one of the following PFAS substance: Polytetrafluoroethylene,Thiophenium, Triphenylsulfonium nonaflate, Trifluoroacetic anhydride				False

BPA Declaration				Response
Product does not contain Bisphenol A (Isopropylidenediphenol)				True

Montreal Protocol				Response
Product does not contain Ozone Depleting Substances based on Annex I to Annex VII of EU REGULATION (EC) No 1005/2009				True

Environmental Protection Agency:Toxic Substances Control Act (TSCA). Section 6(h)				Response
Product does not contain Phenol, isopropylated, phosphate (3:1)				True



Material composition declaration : note : Substance present with less 0.001mg will not be declared in this document						Manufacturing item name	77AA-MY3ZABD		13.2000		6000000.0	1000000.0				
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Dies	M-011 Other inorganic materials	3.716	mg	supplier	die	Silicon(Si)	7440-21-3		3.191	mg	858719	241742				
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.013	mg	3498	985				
				supplier	metallisation	Copper(Cu)	7440-50-8		0.046	mg	12379	3485				
				supplier	metallisation	Cobalt(Co)	7440-48-4		0.014	mg	3767	1061				
				supplier	metallisation	Tantalum(Ta)	7440-25-7		0.009	mg	2422	682				
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.005	mg	1346	379				
				supplier	metallisation	Tungsten(W)	7440-33-7		0.001	mg	269	76				
				supplier	metallisation	Zirconium(Zr)	7440-67-7		0.002	mg	538	152				
				supplier	Passivation	Silicon Nitride (SiN)	12033-89-5		0.014	mg	3767	1061				
				supplier	passivation	Silicon Oxide	7631-86-9		0.093	mg	25027	7045				
				supplier	glass	Aluminium Oxide	1344-28-1		0.001	mg	269	76				
					JIG-R & California 65	glass	Lead-Borate Glass	65997-18-4	7c-I-Electrical and electron	0.327	mg	87998	24773			
							Fiber glass	65997-17-3		0.380	mg	135472	28788			
				Substrate	M-015 Other organic materials	2.805	mg	supplier	core material	Bisphenol F type epoxy resin	9003-36-5		0.210	mg	74866	15909
								supplier	core material	Bismaleimide (B)	105391-33-1		0.126	mg	44920	9545
supplier	core material	Triazine (T)	25722-66-1						0.126	mg	44920	9545				
supplier	core material	Aluminium hydroxide	21645-51-2						0.009	mg	3209	682				
supplier	core material	Zinc hydroxide	20427-58-1						0.002	mg	713	152				
supplier	core material	Calcium sulfate	7778-18-9						0.004	mg	1426	303				
		mg	supplier					Solder mask	Acrylic resin	9003-01-4		0.354	mg	126203	26818	
			supplier					Solder mask	Barium sulfate	7727-43-7		0.049	mg	17469	3712	
			supplier					Solder mask	Silica vitreous	7631-86-9		0.049	mg	17469	3712	
			supplier					Solder mask	Talc	14807-96-6		0.025	mg	8913	1894	
	M-004 Copper and its alloys		mg					supplier	Solder mask	Additive	proprietary		0.015	mg	5348	1136
	M-006 Nickel and its alloys							supplier	metallisation	Copper(Cu)	7440-50-8		1.332	mg	474866	100909
	M-008 Precious metals							supplier	metallisation	Nickel(Ni)	7440-02-0		0.105	mg	37433	7955
								supplier	metallisation	Gold(Au)	7440-57-5		0.019	mg	6774	1439
Die attach-1	M-015 Other organic materials	0.168	mg					supplier	tape	Tin(Sn)	proprietary		0.106	mg	630952	8030
				supplier	tape	Polypropylene	9003-07-0		0.003	mg	17857	227				
				supplier	tape	epoxy resin	29890-82-2		0.017	mg	101190	1288				
				supplier	tape	Propenoate polymer	proprietary		0.034	mg	202381	2576				
				supplier	tape	Bisphenol A diglycidyl ether	1675-54-3		0.008	mg	47619	606				
Die attach-2	M-015 Other organic materials	0.188	mg	supplier	glue	Amorphous silica	7631-86-9		0.079	mg	420213	5985				
				supplier	glue	Polyethylen terephthalate	25038-59-9		0.047	mg	250000	3561				
				supplier	glue	Acrylic resin	9003-01-4		0.031	mg	164894	2348				
				supplier	glue	Epoxyde bisphenol A resin	25068-38-6		0.031	mg	164894	2348				
				supplier	wire	Gold(Au)	7440-57-5		1.560	mg	989848	118182				
Bonding wire	M-008 Precious metals	1.576	mg	0	supplier	wire	Palladium(Pd)	7440-05-3	0.016	mg	10152	1212				
				Encapsulation	M-015 Other organic materials	4.747	mg	supplier	mold compound	Solid Epoxy Resin	proprietary	0.237	mg	49926	17955	
supplier	mold compound	Hardener	proprietary	0.237				mg	49926	17955						
supplier	mold compound	Carbon Black	1333-86-4					0.048	mg	10112	3636					
				supplier	mold compound	Amorphous silica-1	7631-86-9		0.427	mg	89952	32348				